

Title (en)  
ELECTROFORMED COMPONENT MANUFACTURE

Title (de)  
HERSTELLUNG VON GALVANOPLASTIKBAUTEILEN

Title (fr)  
FABRICATION DE COMPOSANTS PAR ÉLECTROFORMAGE

Publication  
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Application  
**EP 06820393 A 20061204**

Priority

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Abstract (en)  
[origin: GB2432847A] A method of forming an electroformed component is described. The method comprises forming a conductive seed layer (figure 1, 5) on a substrate 3 by spraying at least a first solution onto the substrate to form a first conductive layer. A pattern resist 11 is provided over the conductive seed layer (figure 1, 5) and the component is then electroformed. The conductive seed layer (figure 1, 5) may comprise a layer of silver, the substrate may be glass 3 and the component may be a MEMS component such as an inkjet nozzle or a fuel injection nozzle. Apparatus for performing this method is also described.

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